

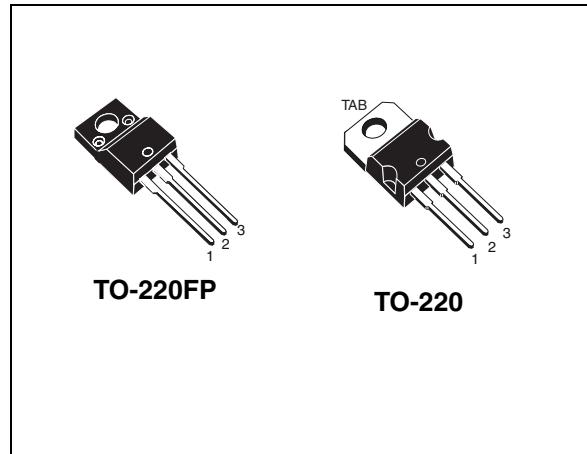
20 A, 600 V fast IGBT with Ultrafast diode

Features

- Very low on-voltage drop ($V_{CE(sat)}$)
- Minimum power losses at 5 kHz in hard switching
- Optimized performance for medium operating frequencies.
- IGBT co-packaged with Ultrafast freewheeling diode

Application

Medium frequency motor drives



Description

This IGBT utilizes the advanced PowerMESH™ process resulting in an excellent trade-off between switching performance and low on-state behavior.

Figure 1. Internal schematic diagram

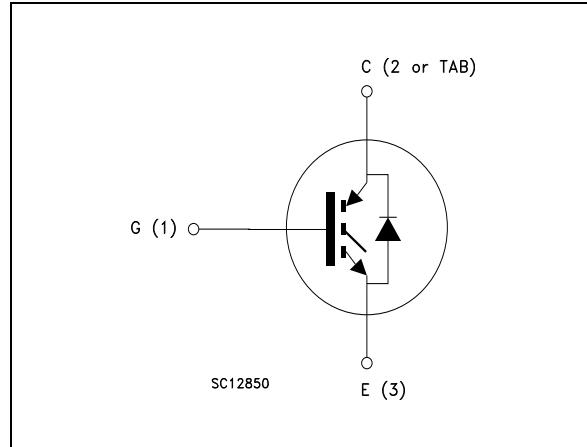


Table 1. Device summary

Order codes	Marking	Package	Packaging
STGF19NC60SD	GF19NC60SD	TO-220FP	Tube
STGP19NC60SD	GP19NC60SD	TO-220	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
2.1	Electrical characteristics (curves)	6
2.2	Frequency applications	9
3	Test circuits	10
4	Package mechanical data	11
5	Revision history	14

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220	TO-220FP	
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600		V
$I_C^{(1)}$	Continuous collector current at $T_C = 25^\circ\text{C}$	40	17	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100^\circ\text{C}$	20	11	A
$I_{CP}^{(2)}$	Pulsed collector current	80		A
$I_{CL}^{(3)}$	Turn-off latching current	80		A
I_F	Diode RMS forward current at $T_c = 25^\circ\text{C}$	20		A
I_{FSM}	Surge non repetitive forward current $t_p = 10\text{ms}$ sinusoidal	50		A
V_{GE}	Gate-emitter voltage	± 20		V
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1 \text{ s}; T_c = 25^\circ\text{C}$)	2500		V
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	130	32	W
T_j	Operating junction temperature	- 55 to 150		$^\circ\text{C}$

1. Calculated according to the iterative formula

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(\max)}(T_{j(\max)}, I_C(T_C))}$$

2. Pulse width limited by maximum junction temperature and turn-off within RBSOA
3. Vclamp = 80% of V_{CES} , $T_j = 150^\circ\text{C}$, $R_G = 10 \Omega$, $V_{GE} = 15 \text{ V}$

Table 3. Thermal data

Symbol	Parameter	Value		Unit
		TO-220	TO-220FP	
R_{thj-c}	Thermal resistance junction-case IGBT	0.96	3.9	$^\circ\text{C/W}$
	Thermal resistance junction-case diode	3	5.5	$^\circ\text{C/W}$
R_{thj-a}	Thermal resistance junction-ambient	62.5		$^\circ\text{C/W}$

2 Electrical characteristics

($T_j = 25^\circ\text{C}$ unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ($V_{GE} = 0$)	$I_C = 1\text{mA}$	600			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{V}, I_C = 12\text{A}$ $V_{GE} = 15\text{V}, I_C = 12\text{A}, T_j = 125^\circ\text{C}$		1.55 1.35	1.9	V V
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 250\ \mu\text{A}$	4.2		6.2	V
I_{CES}	Collector cut-off current ($V_{GE} = 0$)	$V_{CE} = 600\ \text{V}$ $V_{CE} = 600\ \text{V}, T_j = 125^\circ\text{C}$			150 1	μA mA
I_{GES}	Gate-emitter leakage current ($V_{CE} = 0$)	$V_{GE} = \pm 20\text{V}, V_{CE} = 0$			± 100	nA
g_{fs}	Forward transconductance	$V_{CE} = 15\text{V}, I_C = 12\text{A}$		10		S

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies} C_{oes} C_{res}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{CE} = 25\text{V}, f = 1\text{MHz},$ $V_{GE} = 0$	-	1190 135 28.5	-	pF pF pF
Q_g Q_{ge} Q_{gc}	Total gate charge Gate-emitter charge Gate-collector charge	$V_{CE} = 480\text{V}, I_C = 12\text{A},$ $V_{GE} = 15\text{V},$ <i>Figure 20</i>	-	54.5 8.7 25.8	-	nC nC nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r (di/dt)on	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ Figure 21	-	17.5 6.2 1870	-	ns ns A/ μ s
$t_{d(on)}$ t_r (di/dt)on	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ $T_j = 125^\circ C$ Figure 21	-	17 6.5 1700	-	ns ns A/ μ s
$t_{r(Voff)}$ $t_{d(Voff)}$ t_f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ Figure 21	-	90 175 215	-	ns ns ns
$t_{r(Voff)}$ $t_{d(Voff)}$ t_f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480V, I_C = 12A$ $R_G = 10\Omega, V_{GE} = 15V,$ $T_j = 125^\circ C$ Figure 21	-	155 245 290	-	ns ns ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{on} $E_{off}^{(1)}$ E_{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 V, I_C = 12 A$ $R_G = 10 \Omega, V_{GE} = 15 V,$ Figure 19	-	135 815 995	-	μJ μJ μJ
E_{on} $E_{off}^{(1)}$ E_{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 V, I_C = 12 A$ $R_G = 10 \Omega, V_{GE} = 15 V,$ $T_j = 125^\circ C$ Figure 19	-	200 1175 1375	-	μJ μJ μJ

1. Turn-off losses include also the tail of the collector current

Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_F	Forward on-voltage	$I_F = 12 A$ $I_F = 12 A, T_j = 125^\circ C$		2.3 2.0		V V
t_{rr} Q_{rr} I_{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 12 A, V_R = 40 V,$ di/dt=100 A/ μ s Figure 22		31 29.5 1.9		ns nC A
t_{rr} Q_{rr} I_{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 12 A, V_R = 40 V,$ di/dt=100 A/ μ s, $T_j = 125^\circ C$ Figure 22		48.5 70.5 3		ns nC A

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

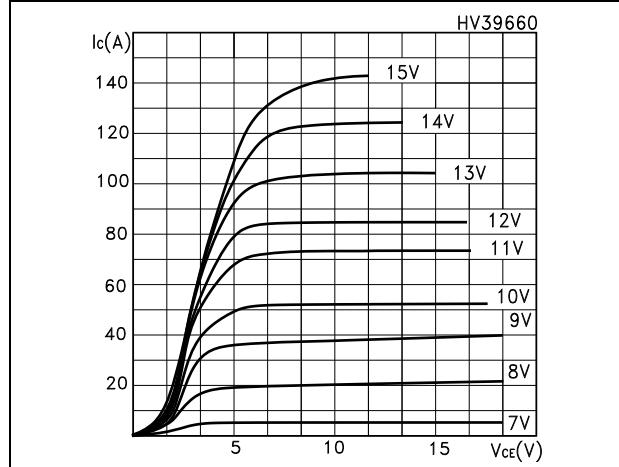


Figure 3. Transfer characteristics

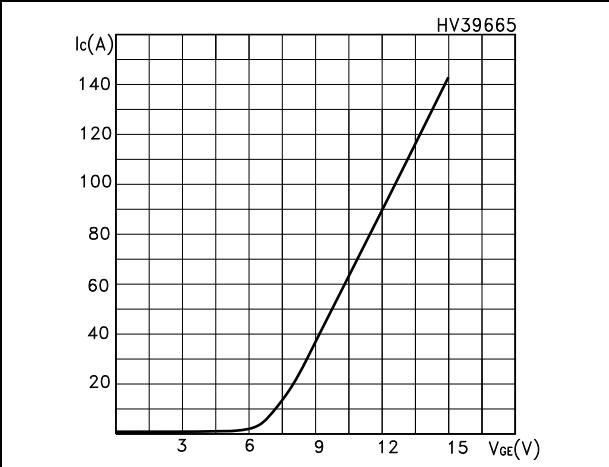


Figure 4. Transconductance

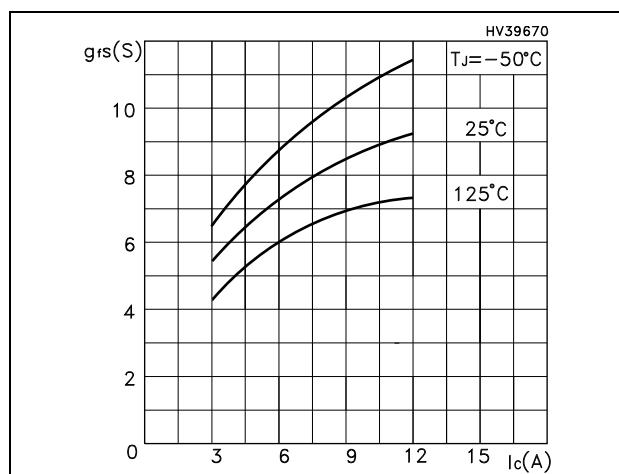


Figure 5. Collector-emitter on voltage vs temperature

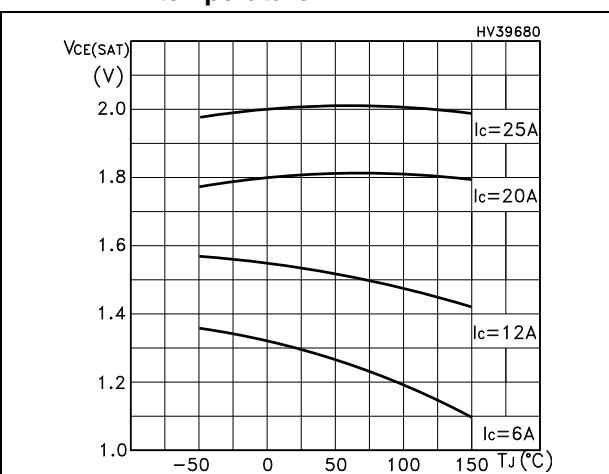


Figure 6. Gate charge vs gate-source voltage

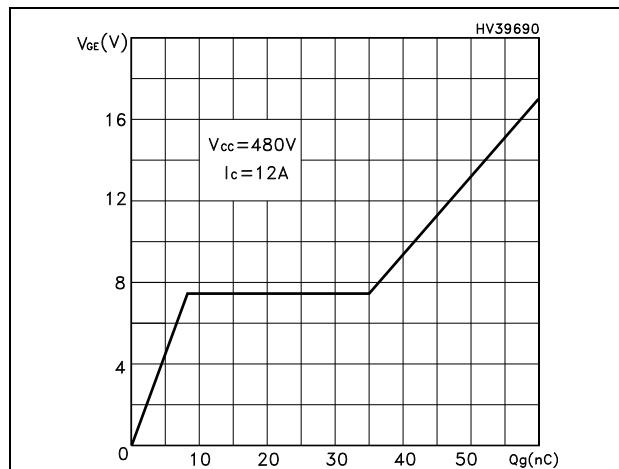


Figure 7. Capacitance variations

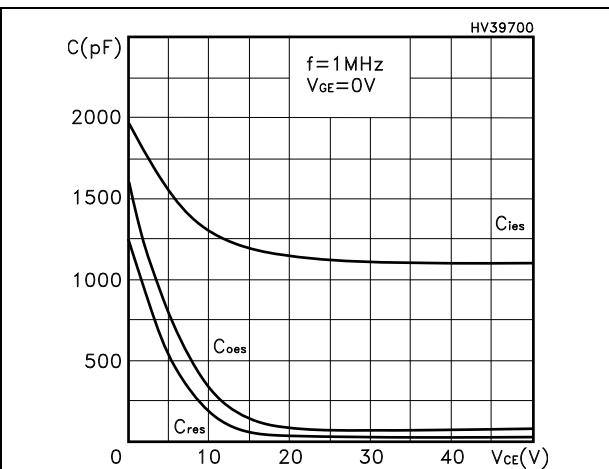


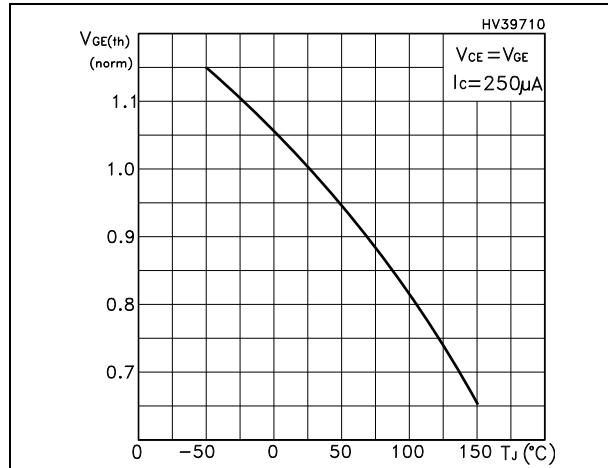
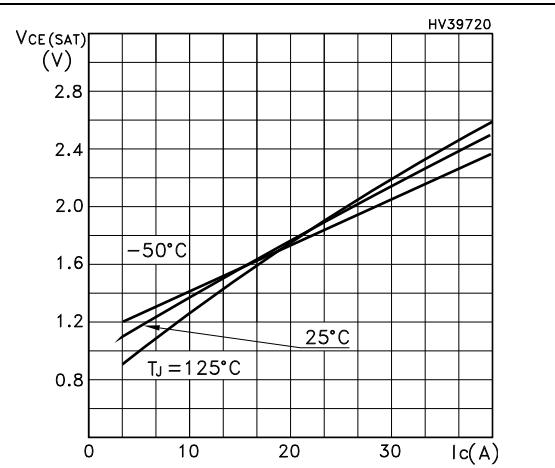
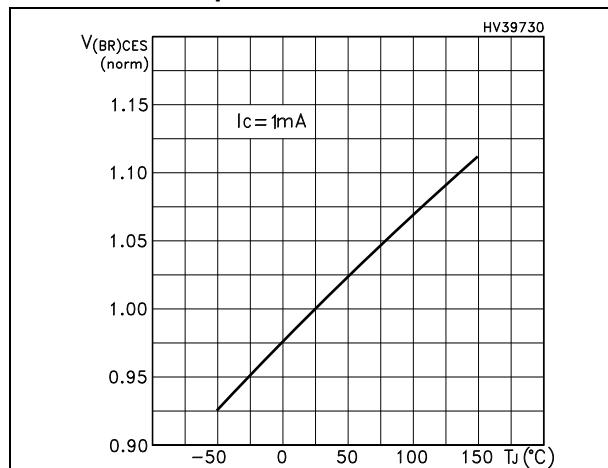
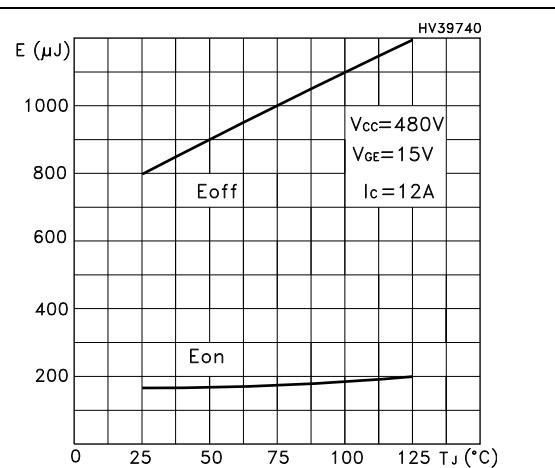
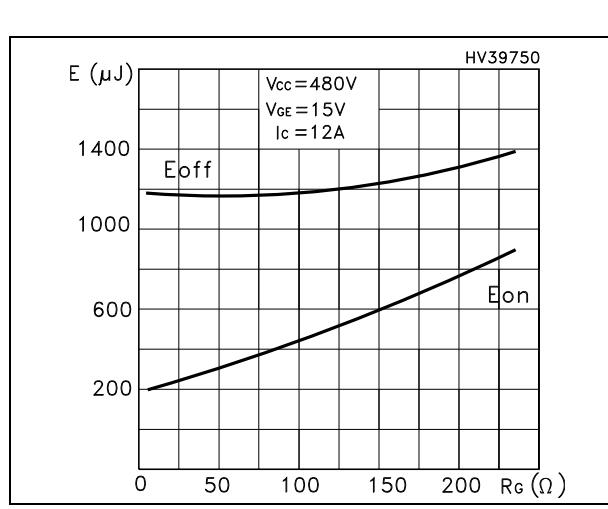
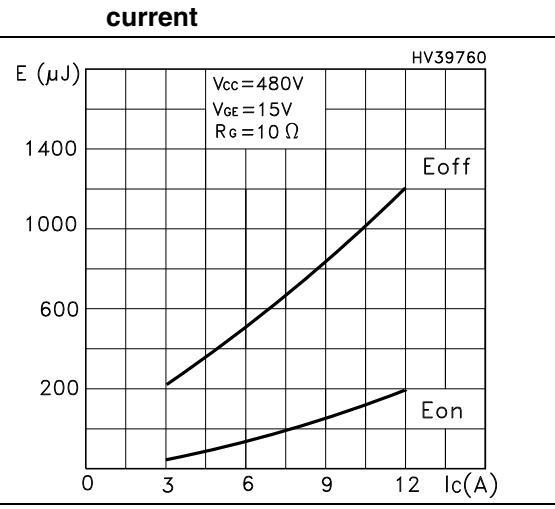
Figure 8. Normalized gate threshold voltage vs temperature**Figure 9. Collector-emitter on voltage vs collector current****Figure 10. Normalized breakdown voltage vs temperature****Figure 11. Switching losses vs temperature****Figure 12. Switching losses vs gate resistance****Figure 13. Switching losses vs collector current**

Figure 14. Turn-off SOA

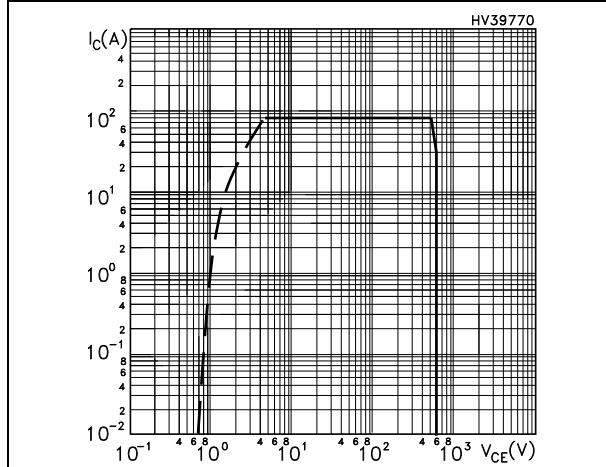


Figure 15. Thermal impedance for TO-220

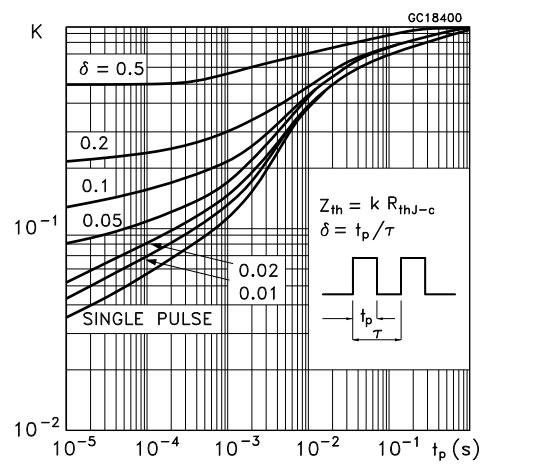


Figure 16. Thermal impedance for TO-220FP

Figure 17. Forward voltage drop versus forward current

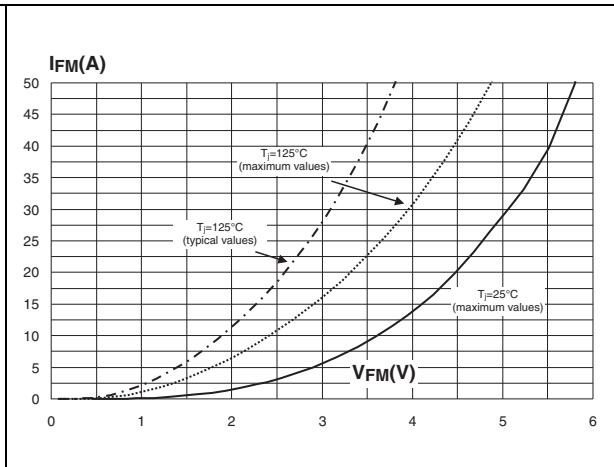
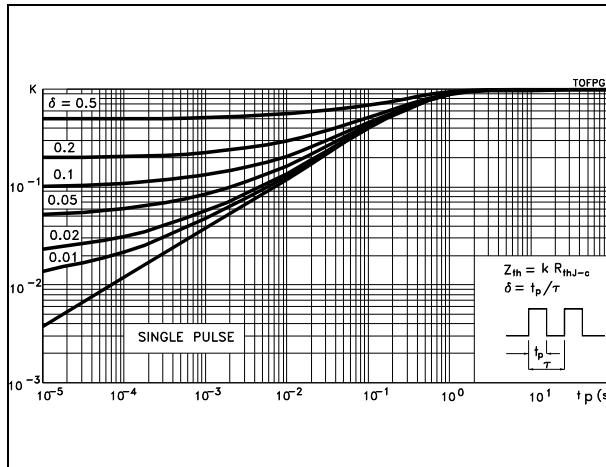
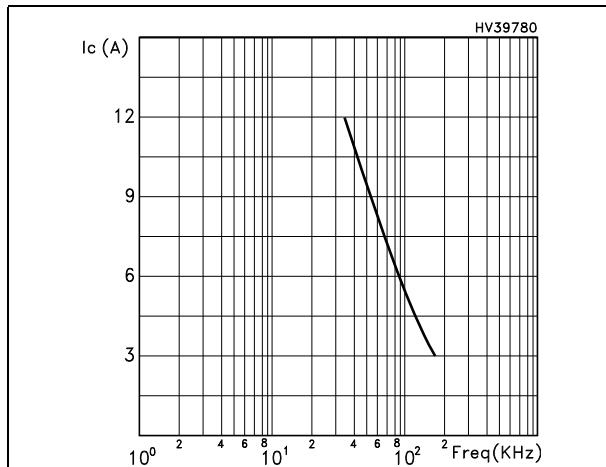


Figure 18. I_C vs. frequency



2.2 Frequency applications

For a fast IGBT suitable for high frequency applications, the typical collector current vs. maximum operating frequency curve is reported. That frequency is defined as follows:

$$f_{MAX} = (P_D - P_C) / (E_{ON} + E_{OFF})$$

- The maximum power dissipation is limited by maximum junction to case thermal resistance:

Equation 1

$$P_D = \Delta T / R_{THJ-C}$$

considering $\Delta T = T_J - T_C = 125 \text{ } ^\circ\text{C} - 75 \text{ } ^\circ\text{C} = 50 \text{ } ^\circ\text{C}$

- The conduction losses are:

Equation 2

$$P_C = I_C * V_{CE(SAT)} * \delta$$

with 50% of duty cycle, V_{CESAT} typical value @ 125°C.

- Power dissipation during ON & OFF commutations is due to the switching frequency:

Equation 3

$$P_{SW} = (E_{ON} + E_{OFF}) * freq.$$

Typical values @ 125°C for switching losses are used (test conditions: $V_{CE} = 480V$, $V_{GE}=15V$, $R_G = 10 \text{ Ohm}$). Furthermore, diode recovery energy is included in the E_{ON} (see [Note 1](#)), while the tail of the collector current is included in the E_{OFF} measurements.

3 Test circuits

Figure 19. Test circuit for inductive load switching

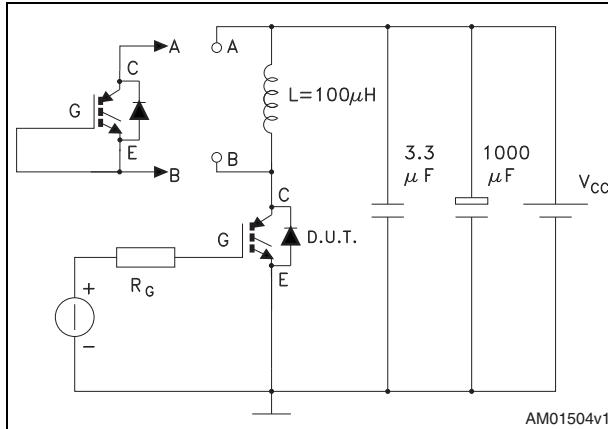


Figure 21. Switching waveform

Figure 20. Gate charge test circuit

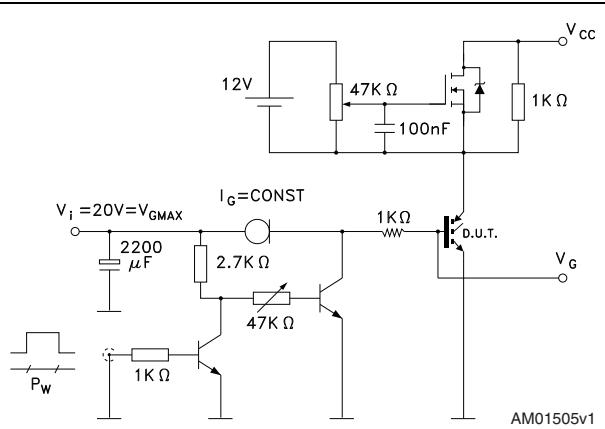
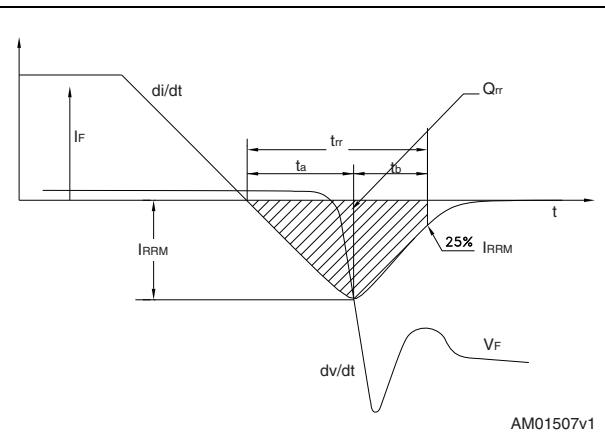
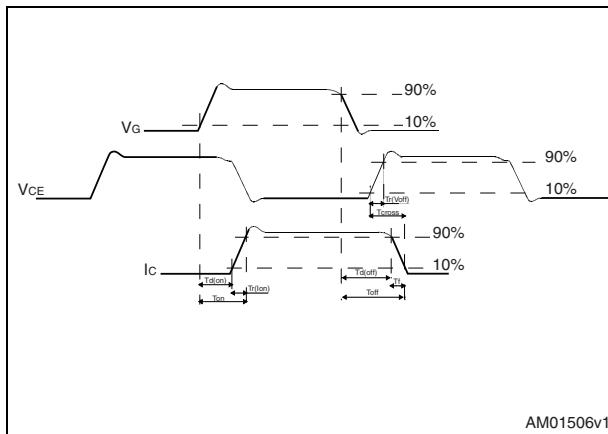


Figure 21. Switching waveform **Figure 22.** Diode recovery time waveform

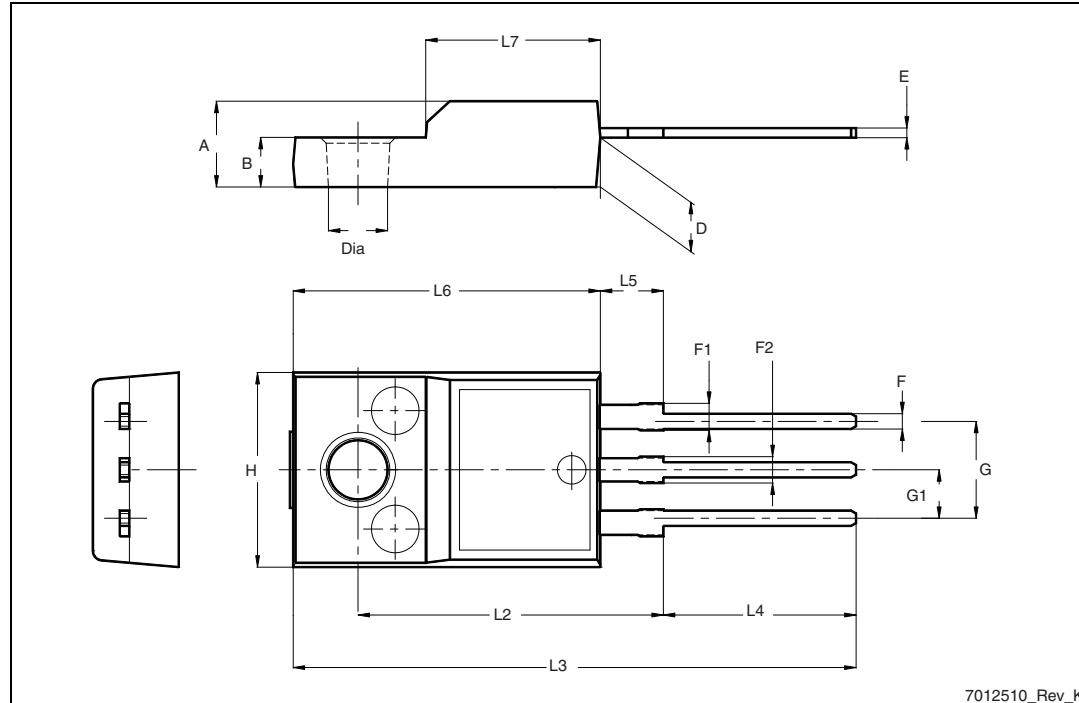


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK is an ST trademark.

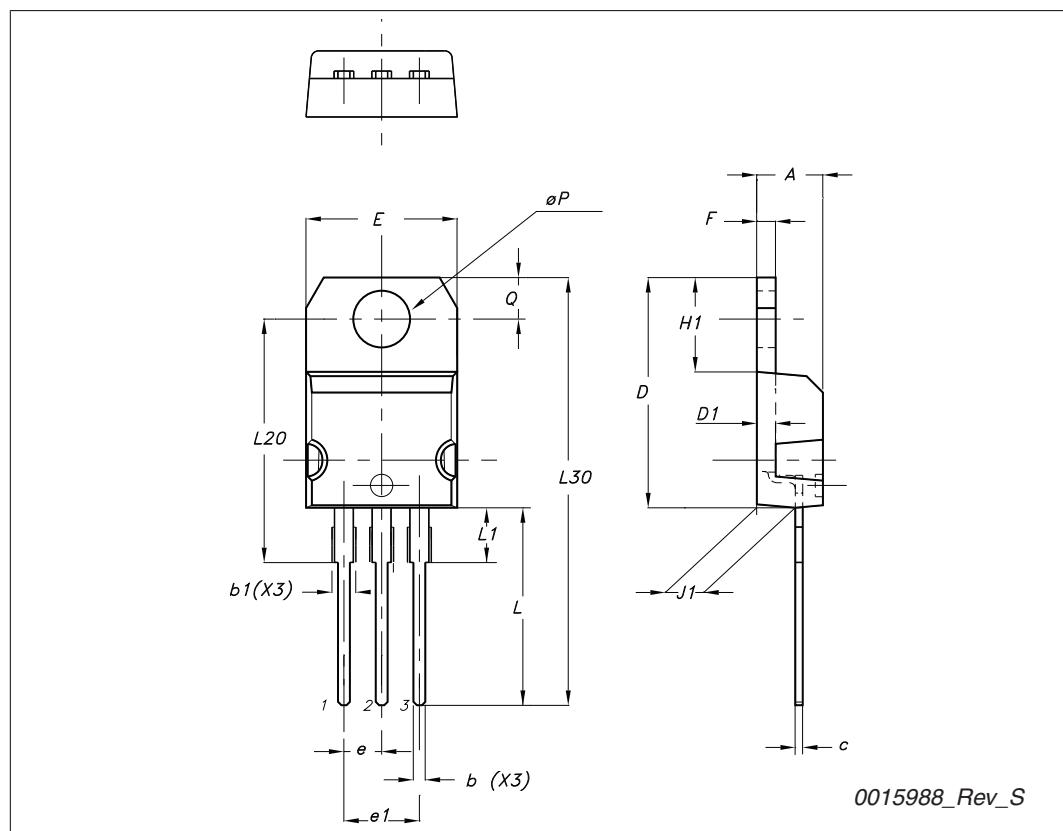
Table 9. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 23. TO-220FP drawing

TO-220 type A mechanical data

Dim	mm		
	Min	Typ	Max
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
$\emptyset P$	3.75		3.85
Q	2.65		2.95



5 Revision history

Table 10. Document revision history

Date	Revision	Changes
02-Jul-2007	1	First release
13-Aug-2007	2	From target to preliminary version
18-Sep-2007	3	Added new section: <i>Electrical characteristics (curves)</i>
05-Nov-2010	4	<ul style="list-style-type: none">– Cover page has been updated– Modified gate threshold voltage range on <i>Table 4: Static</i>– Updated TO-220 mechanical data– Added new package, mechanical data: TO-220FP